| PART INFORMATION | |
|---|---|
| Mfg Item Number | SPC5642AF2MVZ1 |
| Mfg Item Name | PBGA 324 23*23*1.25P1.0 |

| SUPPLIER | |
|---|---|
| Company  Name | Freescale Semiconductor Inc |
| Company Unique ID | 14-141-7928 |
| Response Date | 2016-12-28 |
| Response Document ID | 5241A1.24 |
| Contact Name | Freescale Semiconductor Inc |
| Contact Title | Product Technical Support |
| Contact Phone | 1-800-521-6274 |
| Contact Email | support@freescale.com |
| Authorized Representative | Daniel Binyon |
| Representative Title | EPP Customer Response |
| Representative Phone | 512-895-3406 |
| Representative Email | eppanlst@freescale.com |
| URL for Additional Information | www.freescale.com |

| DECLARATION | |
|---|---|
| EU RoHS | Yes |
| Pb Free | Yes |
| HalogenFree | Yes |
| Plating Indicator | e2 |
| EU RoHS Exemption(s) | |

| MANUFACTURING | |
|---|---|
| Mfg Item Number | SPC5642AF2MVZ1 |
| Mfg Item Name | PBGA 324 23*23*1.25P1.0 |
| Version | ALL |
| Weight | 1.713750 |
| UoM | g |
| Unit Volume | EACH |
| J-STD-020 MSL Rating | 3 |
| Peak Processing Temperature | 260 C |
| Max Time at Peak Temperature | 40 seconds |
| Number of Processing Cycles | 3 |

| **RoHS** | |
|---|---|
| RoHS Directive | 2011/65/EU |
| RoHS Definition | RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium |
| RoHS Legal Definition | Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s),the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply. |
| RoHS Declaration | 1 - Item(s) do not contain RoHS restricted substances per the definition above |
| Supplier Acceptance | Accepted |
| Signature | Daniel Binyon |
| Exemption List Version | 2012/51/EU |
| | |
| List of Freescale Accepted Exemptions | 6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight |
| | 6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight |
| | 6(c) : Copper alloy containing up to 4% lead by weight |
| | 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) |
| | 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications |
| | 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound |
| | 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher |
| | 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC |
| | 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors |
| | 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages |

# MATERIAL COMPOSITION

| **Homogeneous Material** | **Weight** | **SubstanceClass** | **Substance** | **CAS** | **Exemption** | **SubstanceWeight** | **UoM** | **SubPart PPM** | **SubPart%** | **ARTICLEPPM** | **ARTICLE%** |
|---|---|---|---|---|---|---|---|---|---|---|---|
| Epoxy Die Attach | 0.0145 | | | | | | g | | | | |
| Epoxy Die Attach | | Solvents, additives, and other materials | 1,3,5-Triazine-2,4-diamine, 6-[2-(2-methyl-1H-imidazol-1-yl)ethyl] | 38668-46-1 | | 0.00012254 | g | 8451 | 0.8451 | 71 | 0.0071 |
| Epoxy Die Attach | | Plastics/polymers | Phenolic Polymer Resin, Epikote 155 | 9003-36-5 | | 0.0018789 | g | 129579 | 12.9579 | 1096 | 0.1096 |
| Epoxy Die Attach | | Plastics/polymers | 4,4'-Dihydroxydiphenyl | 92-88-6 | | 0.00012254 | g | 8451 | 0.8451 | 71 | 0.0071 |
| Epoxy Die Attach | | Metals | Silver, metal | 7440-22-4 | | 0.01237602 | g | 853519 | 85.3519 | 7221 | 0.7221 |
| Solder Balls - Pb Free, Sn/Ag | 0.2675 | | | | | | g | | | | |
| Solder Balls - Pb Free, Sn/Ag | | Metals | Silver, metal | 7440-22-4 | | 0.0093625 | g | 35000 | 3.5 | 5463 | 0.5463 |
| Solder Balls - Pb Free, Sn/Ag | | Metals | Tin, metal | 7440-31-5 | | 0.2581375 | g | 965000 | 96.5 | 150627 | 15.0627 |
| Die Encapsulant | 0.7571 | | | | | | g | | | | |
| Die Encapsulant | | Plastics/polymers | Other Epoxy resins | - | | 0.045426 | g | 60000 | 6 | 26506 | 2.6506 |
| Die Encapsulant | | Solvents, additives, and other materials | Carbon Black | 1333-86-4 | | 0.007571 | g | 10000 | 1 | 4417 | 0.4417 |
| Die Encapsulant | | Solvents, additives, and other materials | Other inorganic compounds. | - | | 0.015142 | g | 20000 | 2 | 8835 | 0.8835 |
| Die Encapsulant | | Plastics/polymers | Other phenolic resins | - | | 0.037855 | g | 50000 | 5 | 22088 | 2.2088 |
| Die Encapsulant | | Glass | Silica, vitreous | 60676-86-0 | | 0.651106 | g | 860000 | 86 | 379947 | 37.9947 |
| Organic Substrate | 0.592 | | | | | | g | | | | |
| Organic Substrate | | Metals | Barium sulfate | 7727-43-7 | | 0.01295592 | g | 21885 | 2.1885 | 7559 | 0.7559 |
| Organic Substrate | | Metals | Copper, metal | 7440-50-8 | | 0.39745697 | g | 671380 | 67.138 | 231922 | 23.1922 |
| Organic Substrate | | Plastics/polymers | 2,2'-[(1-methylethylidene)bis(4,1-phenyleneoxymethylene)]bisoxirane | 1675-54-3 | | 0.00134502 | g | 2272 | 0.2272 | 784 | 0.0784 |
| Organic Substrate | | Plastics/polymers | Poly[(o-cresyl glycidyl ether)-co-formaldehyde] | 29690-82-2 | | 0.03845987 | g | 64966 | 6.4966 | 22441 | 2.2441 |
| Organic Substrate | | Metals | Gold, metal | 7440-57-5 | | 0.00082051 | g | 1386 | 0.1386 | 478 | 0.0478 |
| Organic Substrate | | Solvents, additives, and other materials | 1-cyanoguanidine | 461-58-5 | | 0.00017582 | g | 297 | 0.0297 | 102 | 0.0102 |
| Organic Substrate | | Solvents, additives, and other materials | 1,1'-(methylenedi-p-phenylene)bismaleimide | 13676-54-5 | | 0.01153808 | g | 19490 | 1.949 | 6732 | 0.6732 |
| Organic Substrate | | Nickel (external applications only) | Nickel | 7440-02-0 | | 0.00485795 | g | 8206 | 0.8206 | 2834 | 0.2834 |
| Organic Substrate | | Plastics/polymers | 4,4'-Isopropylidenediphenol-1-chloro-2,3-epoxypropane concentrate | 25068-38-6 | | 0.03845987 | g | 64966 | 6.4966 | 22441 | 2.2441 |
| Organic Substrate | | Glass | Fibrous-glass-wool | 65997-17-3 | | 0.06153662 | g | 103947 | 10.3947 | 35907 | 3.5907 |
| Organic Substrate | | Solvents, additives, and other materials | Proprietary Material-Other miscellaneous substances. | - | | 0.00397469 | g | 6714 | 0.6714 | 2319 | 0.2319 |
| Organic Substrate | | Metals | Copper phthalocyanine | 147-14-8 | | 0.00010538 | g | 178 | 0.0178 | 61 | 0.0061 |
| Organic Substrate | | Plastics/polymers | Other Non-halogenated Epoxy resins | - | | 0.0203133 | g | 34313 | 3.4313 | 11853 | 1.1853 |
| Bonding Wire, PdCu | 0.0159 | | | | | | g | | | | |
| Bonding Wire, PdCu | | Metals | Copper, metal | 7440-50-8 | | 0.0155979 | g | 981000 | 98.1 | 9101 | 0.9101 |
| Bonding Wire, PdCu | | Metals | Gold, metal | 7440-57-5 | | 0.0000159 | g | 1000 | 0.1 | 9 | 0.0009 |
| Bonding Wire, PdCu | | Metals | Palladium, metal | 7440-05-3 | | 0.0002862 | g | 18000 | 1.8 | 167 | 0.0167 |
| Silicon Semiconductor Die | 0.06675 | | | | | | g | | | | |
| Silicon Semiconductor Die | | Solvents, additives, and other materials | Other miscellaneous substances (less than 5%). | - | | 0.001335 | g | 20000 | 2 | 778 | 0.0778 |
| Silicon Semiconductor Die | | Glass | Silicon, doped | - | | 0.065415 | g | 980000 | 98 | 38170 | 3.817 |

| **LINKS** | |
|---|---|
| MCD LINK | |
| NXP website | http://www.nxp.com |
| GENERAL ENVIRONMENTAL COMPLIANCE LINKS | |
| RoHS signed letter | http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf |
| China RoHS | http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY |
| REACH signed letter | http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf |
| ELV signed letter | http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf |
| Conflict Minerals statement | http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf |
| NXP ENVIRONMENTAL INFORMATION | |
| Environmental Compliance website | http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX |
| FAQ | http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ |
| Technical Service Request | http://www.nxp.com/support/sales-and-support:SUPPORTHOME |
| LINKS TO BLANK IPC1752 FORMS | |
| Blank IPC1752 v1.1 Form | http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf |

IPC1752 XML LINKS

http://www.freescale.com/mcds/SPC5642AF2MVZ1_IPC1752_v11.xml

http://www.freescale.com/mcds/SPC5642AF2MVZ1_IPC1752A.xml